

"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 2827"

0083-0865-2

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

Masashi GOTOH, et al.

SERIAL NO.: 09/119,626

RCE FILED: December 6, 2001

FOR: CIRCUIT BOARD HAVING
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING

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EXAMINER: CUNEO, K.

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GROUP ART UNIT: 2827

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AMENDMENT AFTER FINAL UNDER 37 CFR 1.116

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated July 2, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend Claims 19 and 22 as follows:

19. (Once Amended) A chip part device comprising:

a circuit board including a board main body and a conductive layer formed on said board main body, said conductive layer having a plurality of bonding areas defined by a conductive pattern; and

a chip element mounted on said circuit board, and having a plurality of bump electrodes which are simultaneously joined with said bonding areas by ultrasonic bonding,